



10-17-2008



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Form PTO-1595 (Rev. 09/08)
OMB No. 0651-0027 (exp. 10/31/2008)

RECORDATION FORM COVER
PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

SP. 01. 01

1. Name of conveying party(ies):

Micron Technology, Inc. (9/26/2008)

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: Aptina Imaging Corporation

Internal Address: _____

Street Address: _____

c/o Citco Trustees (Cayman) Limited
Regatta Office Park
West Bay Road

City: Grand Cayman

State: _____

Country: Cayman Islands Zip: Y1-1205

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): in parentheses after inventor name

Assignment Merger Change of Name

Security Agreement Joint Research Agreement

Government Interest Assignment

Executive Order 9424, Confirmatory License

Other _____

4. Application or patent number(s):

A. Patent Application No.(s)

11/217,877

This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Thomas J. D'Amico
DICKSTEIN SHAPIRO LLP

Internal Address: Atty. Dkt.: M4065.1311/P1311

Street Address: 1825 Eye Street, NW

City: Washington

State: DC Zip: 20006-5403

Phone Number: (202) 420-2232

Fax Number: (202) 420-2201

Email Address: DAmicoT@dicksteinshapiro.com

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

Authorized to be charged to deposit account

Enclosed

None required (government interest not affecting title)

8. Payment Information

Deposit Account Number _____

Authorized User Name _____

9. Signature:

Signature

October 10, 2008

Date

Thomas J. D'Amico - 28,371

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 8

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PATENT ASSIGNMENT AGREEMENT

1. Definitions

(a) "Agreement" shall mean this Patent Assignment Agreement.

(b) "Assignee" shall mean **Aptina Imaging Corporation**, a Cayman Islands corporation with offices at c/o Citco Trustees (Cayman) Limited, Regatta Office Park, West Bay Road, Grand Cayman, Y1-1205, Cayman Islands.

(c) "Assignor" shall mean **Micron Technology, Inc.**, a Delaware corporation with offices at 8000 South Federal Way, Boise, ID 83707.

(d) "Effective Date" shall mean October 3, 2008.

(e)



(f)



(g) "Imaging Patents" shall mean those patents identified in ATTACHMENT "A" hereto, including, without limitation, all divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts thereof, and which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(h) "Imaging Patent Applications" shall mean those filed patent applications identified in ATTACHMENT "B" hereto, including, without limitation, all patents, divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(i) "Semiconductor Patents" shall mean those patents identified in ATTACHMENT "D" hereto, including, without limitation, all divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts thereof, and which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(j) "Semiconductor Patent Applications" shall mean those filed patent applications identified in ATTACHMENT "E" hereto, including, without limitation, all patents, divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(k) [REDACTED]

2. [REDACTED]

(a) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Imaging Patents, including all rights to causes of action and remedies related thereto (including the right to sue for past, present or future infringement of rights related to the foregoing and the right to collect damages therefor). Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to issue the Imaging Patents to Assignee and to record assignment of the Imaging Patents to Assignee.

(b) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Intellectual Property rights in the Imaging Patent Applications. Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to record assignment of the Imaging Patent Applications to Assignee.

(c) [REDACTED]

(d) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, and subject further to the restrictions on the Semiconductor Patents set out below, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Semiconductor Patents, including all rights to causes of action and remedies related thereto (including the right to sue for past, present or future infringement of rights related to the foregoing and the right to collect damages therefor). Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to issue the Semiconductor Patents to Assignee and to record assignment of the Semiconductor Patents to Assignee.

(e) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, [REDACTED], Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Intellectual Property rights in the Semiconductor Patent Applications. Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to record assignment of the Semiconductor Patent Applications to Assignee.

(f)

[REDACTED]

[REDACTED]

[REDACTED]

3 [REDACTED]

[REDACTED]

4. [REDACTED]

[REDACTED]

5. [REDACTED]

[REDACTED]

[REDACTED]

6. [REDACTED]

[REDACTED]

7. General

This Agreement shall be effective as of the Effective Date hereof and shall be binding on the respective heirs, assigns, representatives, and successors of Assignor and of Assignee.

[the rest of this page intentionally left blank]

Agreed to by:

Micron Technology, Inc.

Signed: [Signature]

Date: 9/26/08, 2008

Notarization
State of Idaho
County of Ada

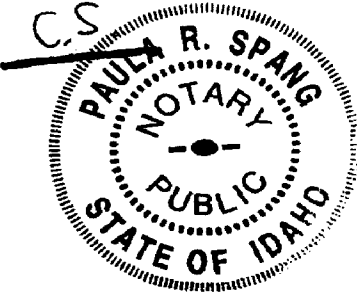
On 9/26/08, before me, Paula R. Spang, personally appeared the above-named Steven R. Appleton

who executed this Assignment in my presence and acknowledged to me that he did so of his own free will and in his authorized capacity for the purposes set forth herein.

Signed: [Signature]

My commission expires: 8/12/11

REVIEWED
MTI LEGAL



Agreed to by:

Aptina Imaging Corporation

Signed: [Signature]

Date: 9/26/08, 2008

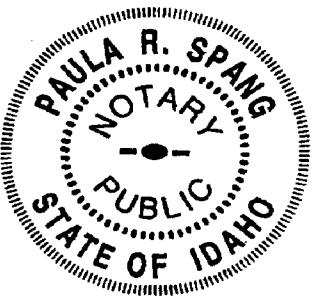
Notarization
State of Idaho
County of Ada

On 9/26/08, before me, Paula R. Spang, personally appeared the above-named Thomas L. Law, Jr.

who executed this Assignment in my presence and acknowledged to me that he did so of his own free will and in his authorized capacity for the purposes set forth herein.

Signed: [Signature]

My commission expires: 8/12/11



[Signature page to the Patent Assignment Agreement]

Aptina Applications

| FILE NUMBER | TITLE | STATUS | COUNTRY NAME | APPLICATION NUMBER | DATE FILED |
|-----------------|---|-----------|--------------------------|--------------------|--------------|
| | MANUFACTURING MICROELECTRONIC IMAGING UNITS AT THE WAFER LEVEL | | | | |
| 2004-0782.00/JP | MICROELECTRONIC IMAGING UNITS AND METHODS OF MANUFACTURING MICROELECTRONIC IMAGING UNITS AT THE WAFER LEVEL | Pending | Japan | | Aug 31, 2006 |
| 2004-0782.00/KR | MICROELECTRONIC IMAGING UNITS AND METHODS OF MANUFACTURING MICROELECTRONIC IMAGING UNITS AT THE WAFER LEVEL | Pending | Republic of Korea | 1020087007940 | Aug 31, 2006 |
| 2004-0782.00/PC | MICROELECTRONIC IMAGING UNITS AND METHODS OF MANUFACTURING MICROELECTRONIC IMAGING UNITS AT THE WAFER LEVEL | Completed | PCT | PCTUS2006034011 | Aug 31, 2006 |
| 2004-0782.00/SG | MICROELECTRONIC IMAGING UNITS AND METHODS OF MANUFACTURING MICROELECTRONIC IMAGING UNITS AT THE WAFER LEVEL | Pending | Singapore | 2008016784 | Aug 31, 2006 |
| 2004-0782.00/TW | MICROELECTRONIC IMAGING UNITS AND METHODS OF MANUFACTURING MICROELECTRONIC IMAGING UNITS AT THE WAFER LEVEL | Pending | Taiwan R.O.C. | 095132427 | Sep 1, 2006 |
| 2004-0782.00/US | MICROELECTRONIC IMAGING UNITS AND METHODS OF MANUFACTURING MICROELECTRONIC IMAGING UNITS AT THE WAFER LEVEL | Allowed | United States of America | 11217877 | Sep 1, 2005 |

